

PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	EMBEDDED PROCESSING/26/16383	
1.3 Title of PCI	Certificate Of Conformity labelling for ST25 NFC tag wafers at Chipbond	
1.4 Product Category	ST25 NFC tag (ST25Txxx)	
1.5 Issue date	2026-05-29	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	David RICHETTO
2.1.2 Marketing Manager	Sylvain FIDELIS
2.1.3 Quality Manager	Mickael DENAIS-ALLICHON

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General (Logistic)	Wafer packing process: labelling, etc	N/A

4. Description of change

	Old	New
4.1 Description	The ST25 NFC tags sawn & bumped wafers assembled at Chipbond subcontractor (Taiwan)...	...will show an additional Certificate Of Conformity (CoC) labelling on the inner box. This label will display the dice quantity and the yield per wafer.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	- Form: Label sticker pasted over the inner box - Fit: No change - Function: No change	

5. Reason / motivation for change

5.1 Motivation	Additional labelling
5.2 Customer Benefit	LOGISTICS IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	N/A
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7. Timing / schedule

7.1 Date of qualification results	2026-05-21
7.2 Intended start of delivery	2026-06-26
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

16383 Public product.pdf
16383 PCI_ST25T_CoC_Chipbond.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	ST25TB04K-AC6G6	

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